

WHAT IS CLAIMED IS:

1. A liquid-crystal-panel driver IC package comprising:
an insulative base;
a liquid-crystal-panel driver IC mounted on the
5 insulative base;

output leads which are provided on the insulative base
on one side of the liquid-crystal-panel driver IC, and which are
connected to the liquid-crystal-panel driver IC; and

input leads which are provided on the insulative base
10 on the other side of the liquid-crystal-panel driver IC, and which
are connected to the liquid-crystal-panel driver IC, wherein

a bending slit is provided on part of the insulative
base where the output leads are provided such that the output
leads remain in the bending slit.

15 2. The liquid-crystal-panel driver IC package according
to Claim 1, wherein

the insulative base is a base tape.

3. The liquid-crystal-panel driver IC package according
to Claim 1, wherein

20 the insulative base is a flexible board.

4. The liquid-crystal-panel driver IC package according
to Claims 1, wherein

the input leads are first input leads and second input
leads which are respectively provided on the insulative base so
25 as to extend bilaterally outwardly generally perpendicularly to

a direction in which the output leads extend from the liquid-crystal-panel driver IC, and

connecting slits are respectively provided on parts of the insulative base where the first and second input leads are provided, respectively, such that the first and second input leads are exposed in the connecting slits.

5. The liquid-crystal-panel driver IC package according to Claims 1, wherein

the input leads are first input leads and second input leads which are respectively provided on the insulative base so as to extend bilaterally outwardly generally perpendicularly to a direction in which the output leads extend from the liquid-crystal-panel driver IC,

a connecting slit is provided on one part of the insulative base where the first input leads are provided such that the first input leads are exposed in the connecting slit, and

a resist-uncoated connecting portion is provided on the other part of the insulative base where the second input leads are provided.

6. The liquid-crystal-panel driver IC package according to Claim 4, wherein

the liquid-crystal-panel driver IC has two identical-signal terminals to which the first and second input leads are connected, respectively, and

the two identical-signal terminals are electrically connected to each other within the liquid-crystal-panel driver IC.

7. The liquid-crystal-panel driver IC package according to Claim 5, wherein

the liquid-crystal-panel driver IC has two identical-signal terminals to which the first and second input leads are connected, respectively, and

the two identical-signal terminals are electrically connected to each other within the liquid-crystal-panel driver IC.

8. A liquid crystal panel module in which the liquid-crystal-panel driver IC packages as defined in Claim 1 are assembled so as to make an array, the liquid crystal panel module comprising:

a first glass substrate and a second glass substrate laminated together with a specified spacing so as to seal liquid crystals therebetween, and to form, on at least one edge side of the first, second glass substrates, a step region for setting therein the liquid-crystal-panel driver IC packages in which each insulative base is bent at the bending slit and folded;

liquid-crystal driving wiring which is provided in the step region of the first, second glass substrates, and to which the output leads of the individual liquid-crystal-panel

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driver IC packages disposed so as to be arrayed along the step region are electrically connected; and

5 a connection board which has connecting lines serving for connecting the input leads of each liquid-crystal-panel driver IC package to each other, and which is disposed on each liquid-crystal-panel driver IC package.

10 9. The liquid crystal panel module in which the liquid-crystal-panel driver IC packages as defined in Claim 4 are assembled so as to make an array, the liquid crystal panel module comprising:

15 a first glass substrate and a second glass substrate laminated together with a specified spacing so as to seal liquid crystals therebetween, and to form, on at least one edge side of the first, second glass substrates, a step region for setting therein the liquid-crystal-panel driver IC packages in which each insulative base is bent at the bending slit and folded; and

20 liquid-crystal driving wiring which is provided in the step region of the first, second glass substrates, and to which the output leads of the individual liquid-crystal-panel driver IC packages disposed so as to be arrayed along the step region are electrically connected, wherein

the connecting slits of mutually adjoining liquid-crystal-panel driver IC packages are superimposed on each other so that the first input leads and second input leads of the

liquid-crystal-panel driver IC packages are electrically connected to each other at the connecting slits.

10. A liquid crystal panel module in which the liquid-crystal-panel driver IC packages as defined in Claim 5 are assembled so as to make an array, the liquid crystal panel module comprising:

a first glass substrate and a second glass substrate laminated together with a specified spacing so as to seal liquid crystals therebetween, and to form, on at least one edge side of the first, second glass substrates, a step region for setting therein the liquid-crystal-panel driver IC packages in which each insulative base is bent at the bending slit and folded; and

liquid-crystal driving wiring which is provided in the step region of the first, second glass substrates, and to which the output leads of the individual liquid-crystal-panel driver IC packages disposed so as to be arrayed along the step region are electrically connected, wherein

the connecting slit and the resist-uncoated connecting portion of mutually adjoining liquid-crystal-panel driver IC packages are superimposed on each other so that the first input leads and second input leads of the liquid-crystal-panel driver IC packages are electrically connected to each other at the connecting slits and the resist-uncoated connecting portions.

11. The liquid crystal panel module according to Claim 8,
wherein

the liquid-crystal-panel driver IC packages are
placed within the step region of the first, second glass
substrates.

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